PCN# : P5CDAAB
Issue Date : Feb. 03, 2016

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples.

Implementation of change:

Expected First Shipment Date for Changed Product :May. 03, 2016

Expected First Date Code of Changed Product :1619

Description of Change (From) :
MDIP packages manufactured at sub-contractors in China and Finish type Comp pb (e3) which is Lead-free compound with Tin plated terminal

Assembly Site	China sub-contractors
Package	MDIP 16L
Lead frame	Cu LF with A194
Die attach material	YixBond 8511F
Wire	1.0 mil Au wire
Mold Compound	ELER-8-560

Description of Change (To) :
Alternate assembly and test sub-contractor in Taiwan and Finish type to Green comp (G3) which is Green compound with Tin plated terminal

Assembly Site	Taiwan sub-contractor
Package	MDIP 16L
Lead frame	Cu LF with A194
Die attach material	Sumitomo CRM-1076DJ-G
Wire	1.0 mil Au wire
Mold Compound	Sumitomo G600F

Reason for Change:
•Improved supply flexibility
•Better quality and yields through equipment and facility upgrades
• Increased automation in handling and inspection in assembly
•Fairchild partnerships with assembly subcontractors
•Best manufacturing practices- access to many customer methods and practices
•Advanced technology for fast ramp of future new products and technologies

Affected Product(s):

KA3525A	KA7500B	KA7500C

Qualification Plan	Device	Package	Process	No. of Lots
Q20140113A	FAN7392N	NMDIP 14L	Bucheon HDG4D	1

Test Description:	Condition:	Standard :	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130°C, 10V	JESD22-A118	96 hrs	0/77
High Temperature Reverse Bias	150°C, 500V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150°C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65°C, 150°C	JESD22-A104	500 cycles	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/5
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11

Qualification Plan	Device	Package	Process	No. of Lots
Q20140113A	KA324	NMDIP 14L	Bucheon BSP1	1

Test Description:	Condition:	Standard :	Duration:	Results:
Autoclave	121°C, 15psi, 100%RH	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130°C, 15V	JESD22-A118	96 hrs	0/77
High Temperature Storage Life	150°C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150°C, 30V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65°C, 150°C	JESD22-A104	500 cycles	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/5
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11

Qualification Plan	Device	Package	Process	No. of Lots
Q20140113A	KA7500C	NMDIP 16L	Bucheon BCH4B	1

Test Description:	Condition:	Standard :	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130°C, 10V	JESD22-A118	96 hrs	0/45
High Temperature Operating Life	115°C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150°C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65°C, 150°C	JESD22-A104	500 cycles	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/5
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11